This certificate is granted and awarded by the authority of the Nadcap Management Council to:

Safran Electronics & Defense

12, Rue Colbert
FOUGERES CEDEX, 35304
France

This certificate demonstrates conformance and recognition of accreditation for specific services, as listed in www.eAuditNet.com on the Qualified Manufacturers List (QML), to the revision in effect at the time of the audit for:

Electronics

Certificate Number: 10651180695
Expiration Date: 31 January 2019

Joseph G. Pinto
Vice President and Chief Operating Officer

SCOPE OF ACCREDITATION

Electronics

Safran Electronics & Defense
12, Rue Colbert
FOUGERES CEDEX, 35304
France

This certificate expiration is updated based on periodic audits. The current expiration date and scope of accreditation are listed at: www.eAuditNet.com - Online QML (Qualified Manufacturer Listing).

In recognition of the successful completion of the PRI evaluation process, accreditation is granted to this facility to perform the following:

AC7120 Rev E - Nadcap Audit Criteria for Circuit Card Assemblies (to be used on audits on/after 9 April 2017)

04– General
05– Outsourced Processes
06– Process Control
07– Visual Acuity
08– Customer Data
09– Electrostatic Discharge (ESD)
10– Material Management
11– Moisture Sensitive Components and Materials
12– Kitting
13.1– In–Process Verification / Inspection: General
13.2– In–Process Verification / Inspection: Visual
13.3– In–Process Verification / Inspection: AOI
13.4– In–Process Verification / Inspection: X–Ray
14.1– Secondary Assembly: Mechanical Part Installation
14.2– Secondary Assembly: Wire Cutting & Stripping
14.3– Secondary Assembly: Jumper Wire Installation
14.4– Secondary Assembly: Stranded Wire Tinning
14.5– Secondary Assembly: Compliant Pin (Press Fit) Connector Installation
14.6– Secondary Assembly: Bonding
15– Cleanliness
16– Final Inspection
17– Rework

AC7120/2 - General Soldering of Printed Board Assemblies (to be used on audits on/after 9 April 2017)

03– General
04– Electronic Component Preparation for Preassembly Process
05.1– Part Placement: General
05.2– Part Placement: Manual
06– Gold Removal
07– Build Through / Build Short
08– Hand Soldering

AC7120/3 - Plated Through Hole Technology (to be used on audits on/after 9 April 2017)

03.1– Part Placement: Operator–Assisted (Semi–Automated)
04– Wave Soldering
05– Selective Soldering

AC7120/4 - Surface Mount Technology (to be used on audits on/after 9 April 2017)

03– Preparation
04– Stencil Printing
05– Automated Part Placement
06– Reflow Soldering

AC7120/6 - Lead Free Soldering (to be used on audits on/after 9 April 2017)

03– Lead–Free Control Plan (LFCP)
04– Process Control
05– Training

AC7120/7 - Conformal Coating of Printed Board Assemblies (to be used on audits on/after 9 April 2017)

04– Material
05– Material and Equipment Compatibility
06– Preparation / Cleaning
07– Application / Drying / Curing
08– Thickness
09– Inspection
10– Rework
11– Training

AC7120/8 - Encapsulation (to be used on audits on/after 9 April 2017)

AC7120/9 - Programming (to be used on audits on/after 9 April 2017)

04– General
05– Component Programming (Prior to Assembly)
06– Circuit Card Assembly Programming

AC7120/10 - Final Testing (to be used on audits on/after 9 April 2017)

04– General